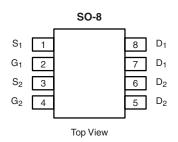


Dual N-Channel 30-V (D-S) MOSFET with Schottky Diode

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)				
30	0.022 at V _{GS} = 10 V	7.5				
	$0.030 \text{ at V}_{GS} = 4.5 \text{ V}$	6.5				

SCHOTTKY PRODUCT SUMMARY						
V _{DS} (V)	V _{SD} (V) Diode Forward Voltage	I _F (A)				
30	0.50 V at 1.0 A	2.0				



Ordering Information: Si4834BDY-T1-E3 (Lead (Pb)-free)

Si4834BDY-T1-GE3 (Lead (Pb)-free and Halogen-free)

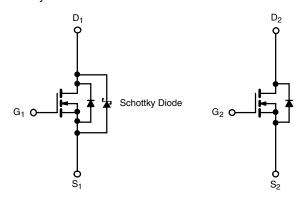
FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- PWM Optimized
- 100 % R_g Tested
- Compliant to RoHS Directive 2002/95/EC



APPLICATIONS

Symmetrical Buck-Boost DC/DC Converter



N-Channel MOSFET

N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted							
Parameter		Symbol	10 s	Steady State	Unit		
Drain-Source Voltage		V_{DS}	30	V			
Gate-Source Voltage		V_{GS}	± 2	V			
Continuous Drain Current /T 150 °C\d	T _A = 25 °C	I _D	7.5	5.7			
Continuous Drain Current (T _J = 150 °C) ^a	T _A = 70 °C		6.0	4.6	^		
Pulsed Drain Current		I _{DM}	30		A		
Continuous Source Current (Diode Conduction) ^a		I _S	1.7	1.7 0.9			
	T _A = 25 °C	P _D	2.0	1.1	w		
Maximum Power Dissipation ^a	T _A = 70 °C	' D	1.3	0.7	VV		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150		°C		

THERMAL RESISTANCE RATINGS								
			MOSFET		Schottky			
Parameter		Symbol	Тур.	Max.	Тур.	Max.	Unit	
Maximum Junction-to-Ambient ^a	t ≤ 10 s	- R _{thJA}	52	62.5	53	62.5		
	Steady State		93	110	93	110	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	35	40	35	40		

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

Si4834BDY

Vishay Siliconix



Parameter	Symbol	Test Conditions	Min.	Typ. ^a	Max.	Unit	
Static							
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$		0.8		3.0	V
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$				± 100	nA
		V _{DS} = 30 V, V _{GS} = 0 V	Ch-1			100	
Zero Gate Voltage Drain Current	I _{DSS}		Ch-2			1	μΑ
Zero date voltage Brain ourient	.D22	V _{DS} = 30 V, V _{GS} = 0 V, T _J = 85 °C	Ch-1			2000	μΛ
		105 co 1, 165 c 1, 15 cc c	Ch-2			15	
On-State Drain Current ^b	$I_{D(on)}$	$V_{DS} = 5 \text{ V}, V_{GS} = 10 \text{ V}$		20			Α
Durin Course On Olate Basistana b	D	$V_{GS} = 10 \text{ V}, I_D = 7.5 \text{ A}$			0.017	0.022	Ω
Drain-Source On-State Resistance ^b	R _{DS(on)}	V _{GS} = 4.5 V, I _D = 6.5 A			0.024	0.030	22
Forward Transconductance ^b	9 _{fs}	V _{DS} = 15 V, I _D = 7.5 A		19		S	
5: 1 5 13/1 h	V _{SD}	I _S = 1 A, V _{GS} = 0 V	Ch-1		0.47	0.5	V
Diode Forward Voltage ^b			Ch-2		0.75	1.2	
Dynamic ^a							
Total Gate Charge	Q_g				7	11	
Gate-Source Charge	Q _{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 7.5 \text{ A}$			2.9		nC
Gate-Drain Charge	Q _{gd}			2.5			
Gate Resistance	R _g			0.5	1.5	2.6	Ω
Turn-On Delay Time	t _{d(on)}				9	15	
Rise Time	t _r	$V_{DD} = 15 \text{ V, R}_{L} = 15 \Omega$		10	17	ns	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 1 \text{ A, V}_{GEN} = 10 \text{ V, R}_g = 6 \Omega$			19		30
Fall Time	t _f			9	15		
Source Drain Powerse Possyery Time	+	I _E = 1.7 A, dI/dt = 100 A/μs	Ch-1		32	55	
Source-Drain Reverse Recovery Time	t _{rr}	i _F = 1.7 A, αί/αι = 100 A/μs	Ch-2		35	55	

Notes:

b. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.

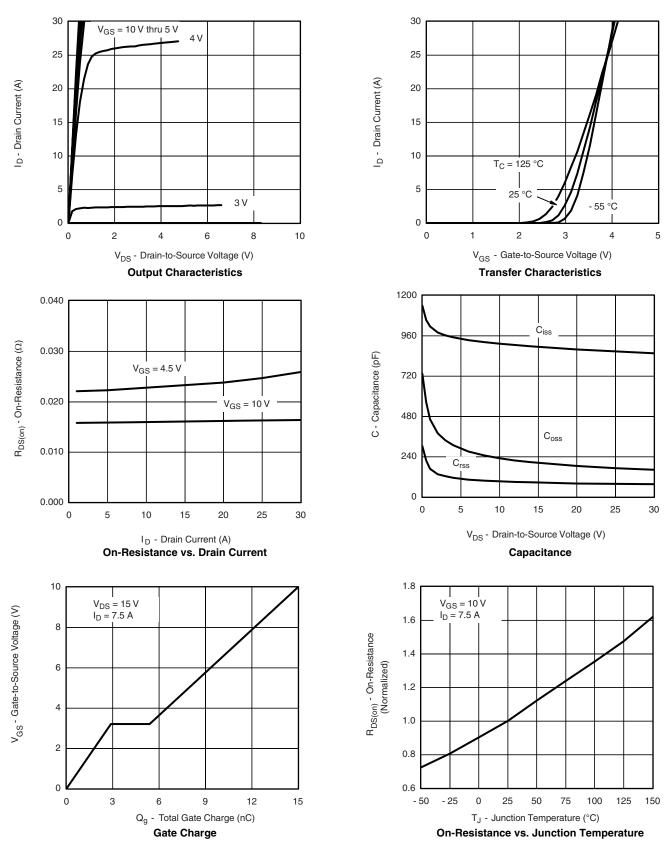
SCHOTTKY SPECIFICATIONS T _J = 25 °C, unless otherwise noted								
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit		
Forward Voltage Drop	V _F	I _F = 1.0 A		0.47	0.50	V		
		I _F = 1.0 A, T _J = 125 °C		0.36	0.42			
Maximum Reverse Leakage Current	I _{rm}	V _R = 30 V		0.004	0.100			
		V _R = 30 V, T _J = 100 °C		0.7	10	mA		
		V _R = - 30 V, T _J = 125 °C		3.0	20			
Junction Capacitance	C _T	V _R = 10 V		50		pF		

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Guaranteed by design, not subject to production testing.

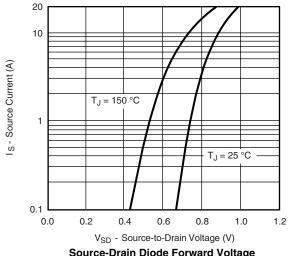


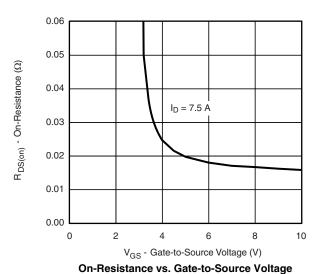
MOSFET TYPICAL CHARACTERISTICS 25 °C unless otherwise noted



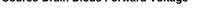
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MOSFET TYPICAL CHARACTERISTICS 25 °C unless otherwise noted

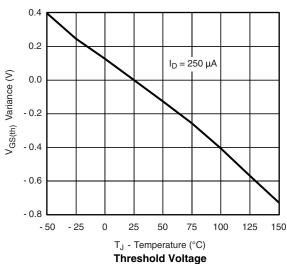


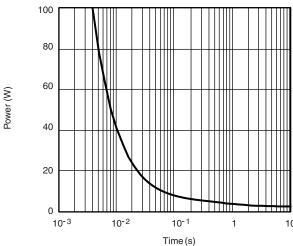


Source-Drain Diode Forward Voltage

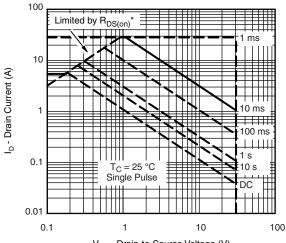








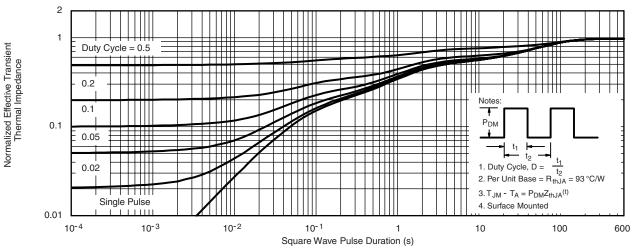
Single Pulse Power, Junction-to-Ambient



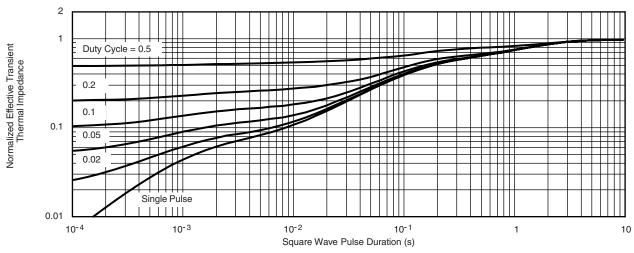
V_{DS} - Drain-to-Source Voltage (V) * V_{DS} > minimum V_{GS} at which $R_{DS(on)}$ is specified



MOSFET TYPICAL CHARACTERISTICS 25 °C unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient

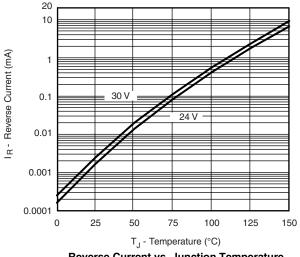


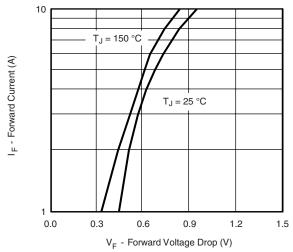
Normalized Thermal Transient Impedance, Junction-to-Foot

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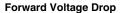


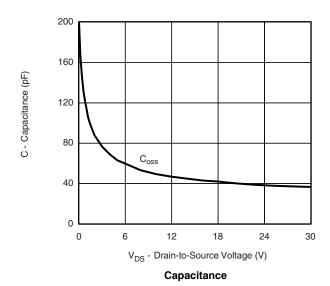
SCHOTTKY TYPICAL CHARACTERISTICS 25 °C unless otherwise noted





Reverse Current vs. Junction Temperature





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